

Attachment A**(S/N: 09/726,141)**

1. (Amended) A case for dissipating heat from an electronic device, comprising:
an electronic circuit board;
a heat generating electronic component disposed on said circuit board; and
a housing positioned about said electronic circuit board and said heat generating electronic component; said housing being made of a net-shaped moldable thermally conductive composite material of a polymer base matrix with thermally conductive filler therein; said housing being in thermal communication with said electronic component with heat being dissipating from said heat generating electronic component and through said housing.

5. (Amended) A case for dissipating heat from an electronic device, comprising:
an electronic circuit board;
a heat generating electronic component disposed on said circuit board;
a housing positioned about said electronic circuit board and said heat generating electronic component; said housing being of a net-shaped moldable thermally conductive composite material of a polymer base matrix with thermally conductive filler therein;
a protrusion emanating from said housing corresponding and aligned with said heat generating electronic component; said protrusion emanating from said housing;
and
said protrusion being in thermal communication with said electronic component with heat being dissipating from said heat generating electronic component and through said housing via said protrusion.

9. (Amended) A case for dissipating heat from an electronic device, comprising:
an electronic circuit board;

a heat generating electronic component, having a top surface, disposed on said circuit board;

an electromagnetic interference shield positioned on said electronic circuit board with said heat generating electronic component residing therebetween; said electromagnetic interference shield including a top surface with an aperture therethrough;

a heat transfer conduit molded into and through said aperture; said heat transfer conduit being made of a thermally conductive material and having a top surface and a bottom surface;

a housing, being made of a net-shaped moldable thermally conductive composite material of a polymer base matrix with thermally conductive filler therein, being in [thermally] thermal communication with said top surface of said heat transfer conduit; said bottom surface of said heat transfer conduit being in thermal communication with said top surface of said heat generating electronic component;

whereby heat is dissipated from said from said heat generating electronic component [through said housing] via said heat transfer conduit through said electromagnetic interference shield and out said housing while said electromagnetic interference shield protects said heat generating electronic component from electromagnetic interference.